



25th International Conference on Electronic Packaging Technology

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Speech subject: **Current Status and Research Progress of Packaging Materials and Processes for Power Electronics**

Speech leader: Dr. Ju XU, Huawei 2012 Laboratory

Speech Description/Objective:

Speech Outline:

Who Should Attend:

Introduction of Speaker:

Ju Xu, Ph.D., who joined the Huawei 2012 Laboratory in 2023 as a senior engineer in the board-level process technology area now. Dr. Xu has been engaged in microelectronic packaging researches including materials, process and new detection technologies, thermal management materials, and thermal functional materials and devices in Microsystem Center at Tyndall National Institute Ireland, the Department of Mechanical Engineering and microelectronic Packaging Center of The Georgia Institute of Technology in United States, and the Micro-Nano Fabrication Laboratory of Institute of Electrical Engineering of the Chinese Academy of Sciences (IEECAS). Xu has been issued awards as the Category A Hundred Talents Program of CAS, the Newton Advanced Fellow of Royal Society UK and Irceet Marie Curie Research Fellow in EU Etc.